PMP11311 REV E1 Bill of Materials

Designator	Quantity	Value	PartNumber	Manufacturer	Description	PackageReference
!PCB1	1		PMP11311	Any	Printed Circuit Board	
C1, C11	2	0.47uF	GRM188R71E474KA12D	MuRata	CAP, CERM, 0.47uF, 25V, +/-10%, X7R, 0603	0603
C2, C12	2	0.022uF	GRM155R71E223KA61D	MuRata	CAP, CERM, 0.022uF, 25V, +/-10%, X7R, 0402	0402
C3, C13	2	0.01uF	GRM155R71E103KA01D	MuRata	CAP, CERM, 0.01uF, 25V, +/-10%, X7R, 0402	0402
C4	1	680pF	GRM155R71H681KA01D	MuRata	CAP, CERM, 680 pF, 50 V, +/- 10%, X7R, 0402	0402
C5	1	270pF	GRM033R71E271KA01D	MuRata	CAP, CERM, 270 pF, 25 V, +/- 10%, X7R, 0201	0201
C6	1	0.01uF	GRM188R71H103KA01D	MuRata	CAP, CERM, 0.01 µF, 50 V, +/- 10%, X7R, 0603	0603
C7	1	0.012uF	GRM188R71H123KA01D	MuRata	CAP, CERM, 0.012 µF, 50 V, +/- 10%, X7R, 0603	0603
C8	1	0.056uF	GRM188R71H563KA93D	MuRata	CAP, CERM, 0.056 µF, 50 V, +/- 10%, X7R, 0603	0603
C14	1	10uF	EMK107BBJ106MA-T	Taiyo Yuden	CAP, CERM, 10uF, 16V, +/-20%, X5R, 0603	0603
C15	1	4.7uF	GRM188R61C475KAAJ	MuRata	CAP, CERM, 4.7uF, 16V, +/-10%, X5R, 0603	0603
C16	1	2.2uF	C1005X5R1A225K050BC	TDK	CAP, CERM, 2.2uF, 10V, +/-10%, X5R, 0402	0402
C21	1	1uF	C1005X5R1E105K050BC	TDK	CAP, CERM, 1 µF, 25 V, +/- 10%, X5R, 0402	0402
C22	1	4.7uF	GRM155R61C475ME11D	MuRata	CAP, CERM, 4.7 µF, 16 V, +/- 20%, X5R, 0402	0402
C23	1	10uF	CL05A106MP5NUNC	Samsung Electro-Mechanics	CAP, CERM, 10 µF, 10 V, +/- 20%, X5R, 0402	0402
C24, C25	2	1uF	GRM155R61A105KE15D	MuRata	CAP, CERM, 1 µF, 10 V, +/- 10%, X5R, 0402	0402
C31	1	4.7uF	GRM155R61C475ME15	MuRata	CAP, CERM, 4.7 µF, 16 V, +/- 20%, X5R, 0402	0402
C32	1	10uF	GRM155R60J106ME11	MuRata	CAP, CERM, 10 µF, 6.3 V, +/- 20%, X5R, 0402	0402
C41	1	2.2uF	GRM155R61A225ME95	MuRata	CAP, CERM, 2.2 µF, 10 V, +/- 20%, X5R, 0402	0402
C42	1	10uF	GRM188R61C106MAALD	MuRata	CAP, CERM, 10 µF, 16 V, +/- 20%, X5R, 0603	0603
C51	1	2.2uF	CL05A225KQ5NNNC	Samsung	CAP, CERM, 2.2 µF, 6.3 V, +/- 10%, X5R, 0402	0402
C52	1	4.7uF	C1005X5R1A475K050BC	TDK	CAP, CERM, 4.7 µF, 10 V, +/- 10%, X5R, 0402	0402
J1	1		22-05-3041	Molex	Header (friction lock), 100mil, 4x1, R/A, TH	4x1 R/A Header
J2, J10, J13, J15, J16, J17, J18	7		PEC03SAAN	Sullins Connector Solutions	Header, 100mil, 3x1, Tin, TH	Header, 3 PIN, 100mil, Tin
J3, J4, J5, J6, J7, J8, J9, J11, J12, J14	10		PEC02SAAN	Sullins Connector Solutions	Header, 100mil, 2x1, Tin plated, TH	Header, 2 PIN, 100mil, Tin
L1	1		WR222230-26M8-G	TDK	Wireless Power Charging Receiver Coil	Wireless Power Charging Receiver Coil
L2	1	2.2uH	MDT2012-CH2R2N	Toko	Inductor, Multilayer, 2.2 µH, 1.3 A, 0.245 ohm, SMD	Inductor, 2x1x1.25mm
L3	1	2.2uH	DFE201210U-2R2M=P2	Toko	Inductor, Shielded, Metal Composite, 2.2 µH, 1.4 A, 0.19 ohm, SMD	2x1.2mm
L4	1	10uH	VLS252010HBX-100M-1	TDK	Inductor, Wirewound, Ferrite, 10 µH, 0.68 A, 0.46 ohm, SMD	2.5x1x2mm
L5	1	1uH	MDT2012-CH1R0M	Toko	Inductor, Multilayer, 1 µH, 1.4 A, 0.2 ohm, SMD	Inductor, 2x1x1.25mm
R1	1	845	CRCW0201845RFKED	Vishay-Dale	RES, 845, 1%, 0.05 W, 0201	0201
R2	1	20.0k	CRCW020120K0FKED	Vishay-Dale	RES, 20.0 k, 1%, 0.05 W, 0201	0201
R3	1	196	CRCW0201196RFKED	Vishay-Dale	RES, 196, 1%, 0.05 W, 0201	0201
R4	1	10.0k	MCR006YRTF1002	Rohm	RES, 10.0 k, 1%, 0.05 W, 0201	0201
R21, R22	2	2.00	CRCW06032R00FKEA	Vishay-Dale	RES, 2.00 ohm, 1%, 0.1W, 0603	0603
R23, R24	2	49.9k	CRCW040249K9FKED	Vishay-Dale	RES, 49.9 k, 1%, 0.063 W, 0402	0402
R25	1	499	CRCW0402499RFKED	Vishay-Dale	RES, 499 ohm, 1%, 0.063W, 0402	0402
R26, R27	2	100k	CRCW0402100KFKED	Vishay-Dale	RES, 100 k, 1%, 0.063 W, 0402	0402
R41, R51	2	1.0Meg	CRCW06031M00JNEA	Vishay-Dale	RES, 1.0 M, 5%, 0.1 W, 0603	0603
S1	1		B3U-1000P	Omron Electronic Components	SWITCH TACTILE SPST-NO 0.05A 12V	3x1.6x2.5mm

Designator	Quantity	Value	PartNumber	Manufacturer	Description	PackageReference
SH-J1, SH-J2, SH-J3, SH-J4, SH-J5, SH-J6, SH-J7	7	1x2	SNT-100-BK-G	Samtec	Shunt, 100mil, Gold plated, Black	Shunt
U1	1		BQ51003YFPR	Texas Instruments	Highly Integrated Wireless Receiver Qi (WPC v1.1) Compliant Power Supply, YFP0028APAL	YFP0028APAL
U2	1		BQ25120YFF	Texas Instruments	YFF0025AWAW	YFF0025AWAW
U3	1		TPS62743YFPR	Texas Instruments	360nA IQ Chip-Scale Step Down Converter, YFP0008AGAC	YFP0008AGAC
U4	1		TPS61046YFFR	Texas Instruments	28-V Output Voltage Boost Converter in WCSP Package, YFF0006AAAA	YFF0006AAAA
U5	1		TPS61240YFFR	Texas Instruments	3.5-MHz High Efficiency Step-Up Converter, YFF0006AEAE	YFF0006AEAE
FID1, FID2, FID3	0		N/A	N/A	Fiducial mark. There is nothing to buy or mount.	Fiducial

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